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(54) **SEMICONDUCTOR DEVICE**

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ABSTRACT

A semiconductor device is provided. The semiconductor device may include a heat dissipation pad that is formed such that the upper surface is exposed to the outside of a molding portion, a first lead frame that is formed on the left side of the heat dissipation pad so as to be spaced apart from the heat dissipation pad and includes a first portion extending in an upward and downward direction and a second portion protruding in a right direction, second lead frames that are formed on the right side of the heat dissipation pad, a first connection part that is formed so as to be connected to both of the lower surface of the heat dissipation pad and the lower surface of the second portion of the first lead frame, a semiconductor chip that is formed on the lower surface of the heat dissipation pad, and a second connection part that connects the semiconductor chip and the second lead frames.

